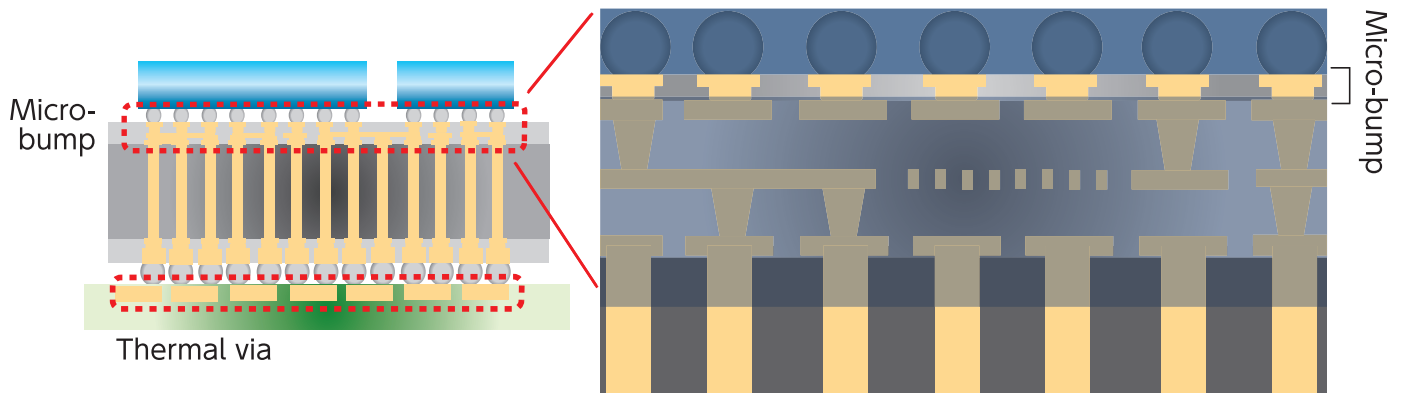
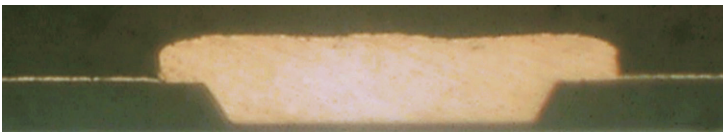


Acid copper plating additive to low aspect ratio via filling for high current density, high heat radiation

TOP LUCINA SD

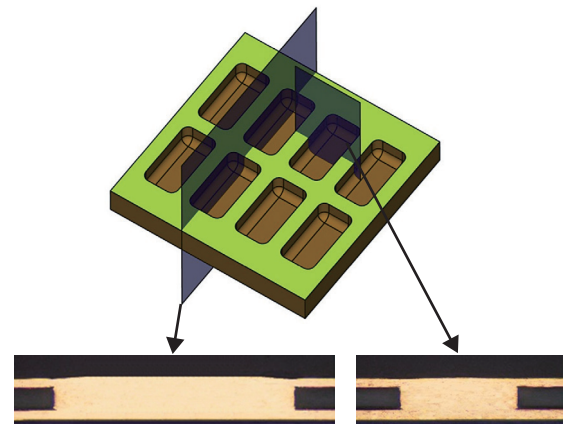


Micro-bump filling



Long side aperture diameter 40 μm ,
Via depth 5 μm
Current density 1.5 A/dm²,
Plating time 15 min

Thermal via filling



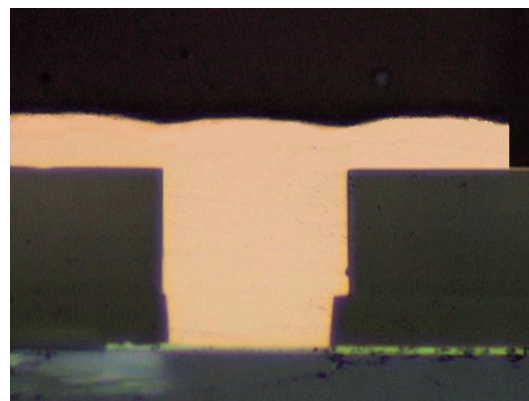
50×100 μm , via depth 30 μm
Current density 1.5 A/dm²,
Plating time 60 min

For low noise, high current density, high heat radiation

Trench filling



Aperture diameter 50 μm , via depth 55 μm



Surface thickness 20 μm